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(71)Applicant : **MATSUSHITA  
ELECTRONICS CORP**

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(72)Inventor : **HIRAMOTO MASAO  
MIZUNO HIROYUKI**

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### (54) MANUFACTURE OF SOLID-STATE IMAGE PICKUP DEVICE

(57)Abstract:

PURPOSE: To project the whole beams transmitting each beam-condensing structure to a photodiode by joining the beam-condensing structures and a solid-state image pickup element through beams and a heat-reactive resin, applying heat after the projection of beams and curing the resin.

CONSTITUTION: Incident beams 19 vertically projected from the transmitting glass substrate 11 side are refracted on the interface between a protective film 14 and a resin layer 15, reach a corresponding diode 16, and are reflected partially. The layer 15 begins to cure at that time while a refractive index also begins to change. The projection of beams is stopped, and the whole is heated temporarily. Regions 17 having a refractive index n1 and regions having a refractive index n2 are formed in the layer 15 by the heating. When the diaphragm of a lens is changed extending over F11□F1.4 and beams are projected to a solid-state image pickup element manufactured in this manner, the regions 17 function as optical waveguides, thus resulting in a projection to the diodes 16 of the whole incident beams.

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